

IN THE CLAIMS:

Amend the pending claims and add new claims as follows:

Claims 1 – 13 (canceled.)

14. (new) A substrate for mounting semiconductor device, comprising:
plural semiconductor-mounting substrate portions, each for mounting a semiconductor device,
a connecting portion for connecting said plural substrates; and
a registration mark portion,
wherein said semiconductor-mounting substrate portion comprises wirings that include an external connection terminal and a wire bonding terminal provided in an outer side than said external connection terminal, and said connecting portion comprises an electrically conductive layer.
15. (new) A substrate for mounting a semiconductor device according to claim 14, wherein said electrically conductive layer and said wiring are made of the same material.
16. (new) A substrate for mounting a semiconductor device as claimed in claim 14, wherein nickel and gold are plated on a surface of said wiring.
17. (new) A substrate for mounting a semiconductor device as claimed in claim 15, wherein nickel and gold is plated on a surface of said wiring.
18. (new) A method of fabricating a substrate for mounting a semiconductor device thereon, comprising:
plural semiconductor- mounting substrate portions, each for mounting a semiconductor device;
a connecting portion for connecting said plural substrate portions and having an electrically conductive layer; and
a registration mark portion,
wherein said semiconductor-mounting substrate portion comprises wirings that include an external connection terminal and a wire bonding terminal provided in outer side than said external connection terminal, and

wherein said fabrication method comprises a step of forming said conductive layer of said wirings and said connecting portions on a resin base material in a lump.

19. (new) A method of fabricating a substrate for mounting a semiconductor device thereon according to claim 18, further comprising a step of; forming said wirings and said conductive layer by plating.
20. (new) A method of fabricating a substrate for mounting semiconductor device thereon according to claim 18, further comprising a step of plating the surface of said wirings with nickel and gold.
21. (new) A method of fabricating a substrate for mounting semiconductor device thereon according to claim 19, further comprising a step of plating the surface of said wirings with nickel and gold.
22. (new) A method of manufacturing a semiconductor package comprising steps of:
mounting a semiconductor device on said substrate for mounting the semiconductor device by a die-bonding material;
connecting a connection terminal of said semiconductor device to said wire bonding terminal with bonding wire;
sealing said semiconductor device with an encapsulating resin; and
forming a solder bump in said external connection terminal;
wherein said substrate for mounting the semiconductor device is the substrate according to any one of claims 14-17 or the substrate manufactured according to the fabricating method as claimed in any one of claims 18-20.
23. (new) A method of fabricating a semiconductor package according to claim 21, wherein said die bond material is a die bonding tape.